

DSS316S-D5



FEATURES

- Storage server supports Dual Intel® Xeon® SP Skylake up to 2TB DDR4
- Four hot-swappable 60mm fan modules per motherboard module
- Support two hot-swap MB Modules each with Xeon DP server boards in one system as unified redundant controllers
- HA Redundant Cluster-in-a-Box solution with PCIe NTB and GbE heartbeat

SPECIFICATIONS

Processor Support	Each Node: Supports Intel® Xeon® SP Skylake up to 205W TDP socket LGA3647
Chipset	Intel® C621 chipset
Memory Support	Each Node: Supports up to 16x DIMMs DDR4 RDIMM/RDIMM 3DS/LRDIMM/LRDIMM 3DS 2666
Expansion Slot	Each Node: 2x PCIe Gen3 x 8 slots; 1x PCIe Gen3 x 16 slots; 1x PCIe Gen3 x16 OCP Storage Mezz.; 1x PCIe Gen3 x16 OCP NIC
Storage	Each node: 36 ports 12G SAS Expander with 3 SFF8643 Connectors
Drive Bays	16 hot-swap 3.5" 12G/6G SAS/SATA drive bay Each node: 2x internal 2.5" 7mm for OS drive bays
Network	Each Node: 2x GbE ports, 1x GbE dedicated for IPMI
Power	1+1 1200W AC/DC 80 Plus Redundant PSU under 220V AC optional -48V DC input available upon request



Supported OS	Windows 2012 R2, RHEL 6.5, SLES 11 SP3, Windows 2008 R2, VMWare ESXi 5.5, FreeBSD 9.2 Centos 6.5; For other OS please contact us
Front Panel	Power On/OFF with LED, reset Switch, NMI switch, Locate Switch with LED, 4xLAN LED, Warning LED
Rear I/O	Each Node: 2x USB 3.0 ports; 2x USB 2.0 ports; 1x DB-9 COM Connector; 1x VGA port, 2x GbE ports
Cooling	Each node: 4x 60mm fans
Other Features	Dedicated GbE for IPMI 2.0
Weight	Gross: 37.95KG/83.5LBS; Net: 33.6KG/74LBS
Dimension	System: 27"x19"x5.25" (LxWxH) Packaging: 38"x 25.5"x15" (LxWxH)
Logistic	HTS Code: 8473 30 5100; ECCN: 4A994
Environmental	Operating Temperature: 0°C to 35°C Non-Operating Temperature: -20°C to 70°C Humidity: 5% to 95% non-condensing
Compliance	CE, FCC Class A, RoHS 6/6 compliant

ORDERING INFO

BD31633D5TY18-A 3U 16 BAYS 3.5" HDD 12G SAS REDUNDANT NODE DUAL XEON SP 1200W HRP

